

FIG. 1

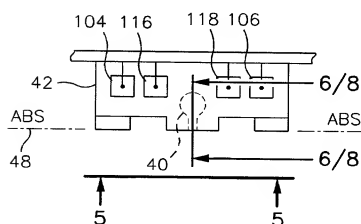


FIG. 2

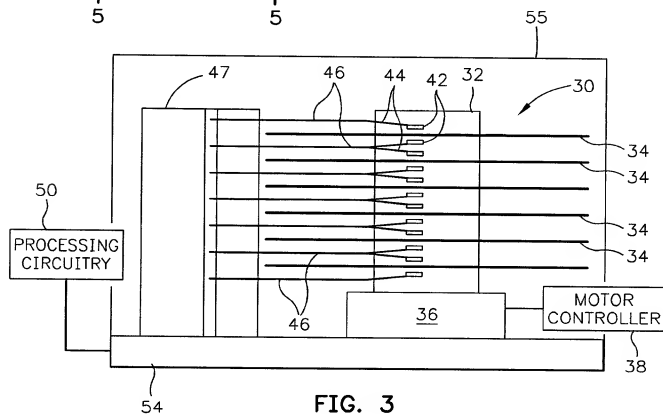


FIG. 3

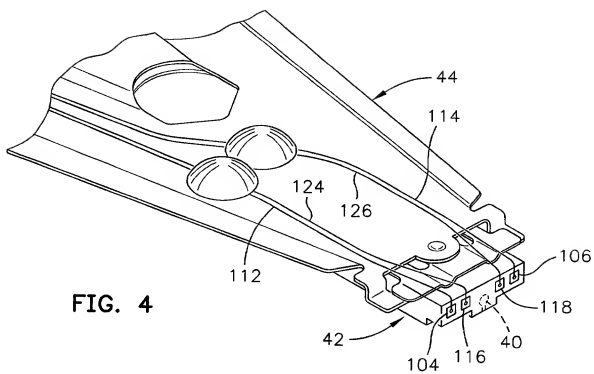


FIG. 4

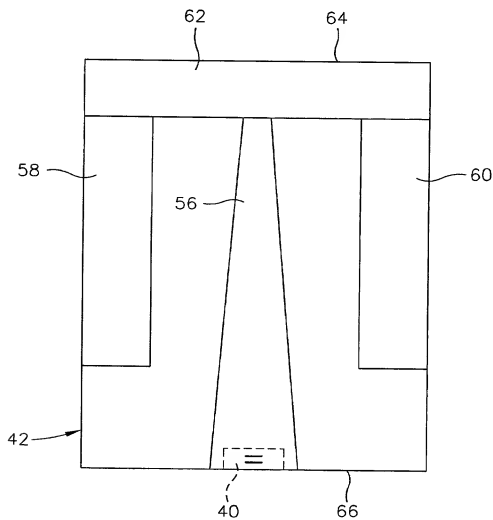
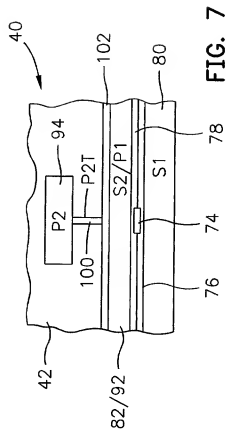
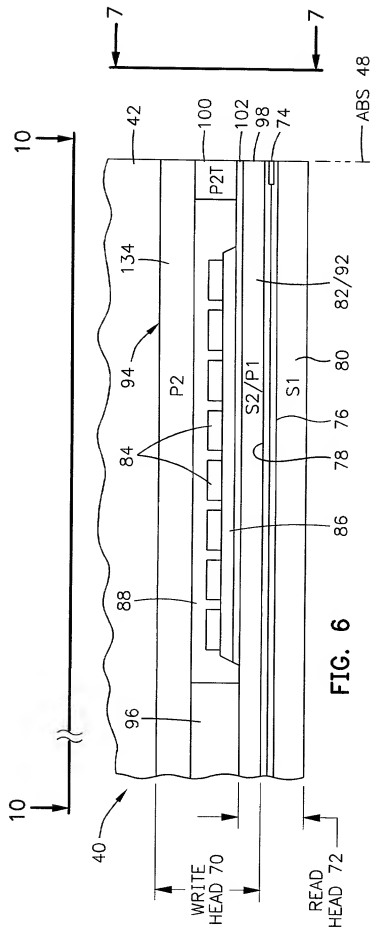
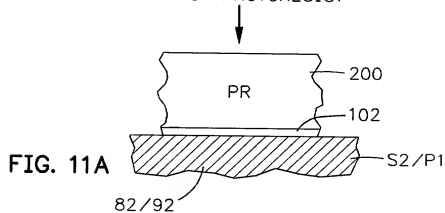


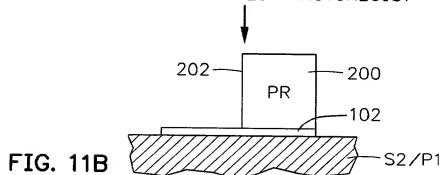
FIG. 5



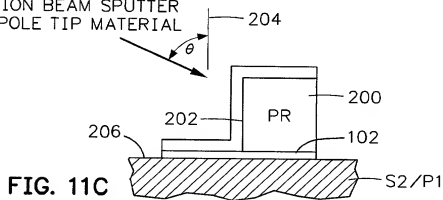
SPIN ON PHOTORESIST



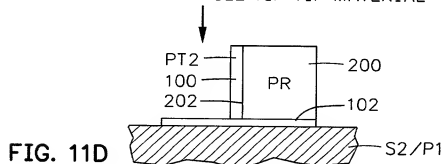
EXPOSE AND DEVELOP PHOTORESIST

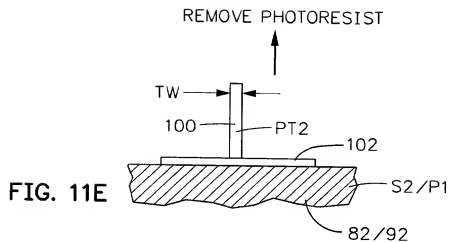


ION BEAM SPUTTER
POLE TIP MATERIAL

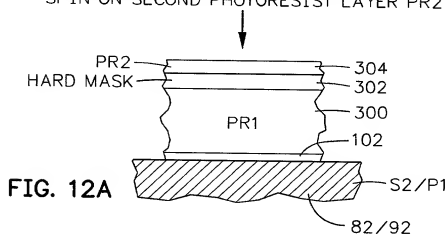


ION MILL AWAY FLAT POLE TIP TIP MATERIAL

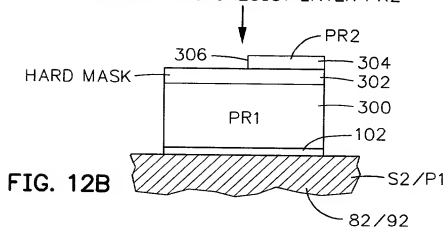




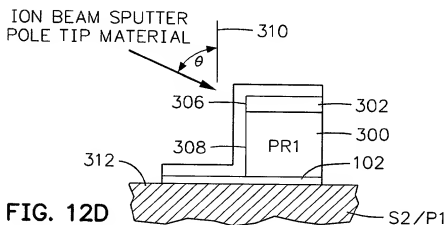
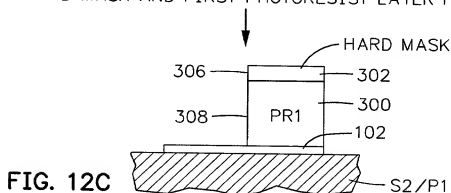
SPIN ON AND HARD BAKE FIRST PHOTORESIST LAYER PR1,
SPUTTER DEPOSIT HARD MASK AND
SPIN ON SECOND PHOTORESIST LAYER PR2



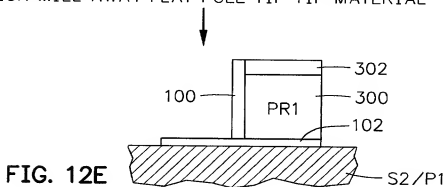
EXPOSE AND DEVELOP
SECOND PHOTORESIST LAYER PR2



RIE SECOND PHOTORESIST LAYER PR2,
HARD MASK AND FIRST PHOTORESIST LAYER PR1



ION MILL AWAY FLAT POLE TIP TIP MATERIAL



REMOVE FIRST PHOTORESIST LAYER PR1

